

Important Dates

Submission Deadline	June 10, 2021
Notification Deadline	June 25, 2021
Registration Deadline	July 01, 2021

Submission Methods

1. Online Submission System

(<http://confsys.iconf.org/submission/icmsn2021>)

2. Send directly to: icmsn@cbees.net

For more information about submission, please visit:

<http://www.icmsn.org/sub.html>

Publication



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ICMSN 2018	Materials Science Forum (Vol. 962) ISBN: 978-3-0357-1416-6
ICMSN 2017	IOP Conference Series: Materials Science and Engineering (Vol. 230) ISSN: 1757-8981

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Conference Topics

1. Nanomaterials
2. Electronic Materials
3. Material Chemistry
4. Materials Processing Engineering
5. Structural Material

For more topics, please visit:

<http://www.icmsn.org/cfp.html>

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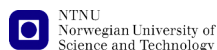
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